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| **Reader enquiries:** | **Press contact:** |
| **congatec AG** | **SAMS Network**  |
| Christian Eder | Michael Hennen |
| Phone: +49-991-2700-0 | Phone: +49-2405-4526720 |
| info@congatec.com[www.congatec.com](http://www.congatec.com/) | info@sams-network.com[www.sams-network.com](http://www.sams-network.com) |

*Text available at:* [*http://www.congatec.com/press*](http://www.congatec.com/press)

**Press release**

congatec presents its roadmap to bring 10 GbE to the industrial fields

**congatec begins the industrial market transition
to 10 GbE bandwidth**

**Deggendorf, Germany, September 6, 2017 \* \* \***congatec – a leading technology company for embedded computer modules, single board computers, and embedded design and manufacturing services – announces its new extended roadmap for bringing 10 GbE interconnectivity to the industrial fields. Developed to enable embedded system engineers to design small form factor edge nodes with a low power envelope of less than 20 watts, congatec is breaking new ground to realize the industry vision of entirely enclosed, fanless infrastructure components. Application areas for these low-power x86 nodes for gateway, edge, and fog computing can be found in numerous IoT applications ranging from vision system infrastructure for public safety to real-time smart data servers in industry 4.0 applications to rugged telecom and network equipment, such as small cells, factory gateways, and storage systems. Roadmap details will be featured at the UK’s Engineering Design Show in Coventry (Stand H6) and attendees will have the opportunity to request platforms quickly through congatec’s exclusive early access program.

“With our COM Express Type 7 modules based on the Intel® Xeon® D processor technology, we have introduced 10 GbE for applications on industrial server level. This is the first phase of bringing 10 GbE to the industrial fields, and sets the stage for smarter devices on the infrastructure and process levels, featuring low-power designs capable of executing multiple 10 GbE interfaces,” explains Christian Eder, Director Marketing at congatec. “To drive this significant shift forward effectively, we formed a stable roadmap of modules, designed to steadily expand 10 GbE capabilities within the broad spectrum of industrial applications.”

congatec’s new platforms deliver their 10 GbE bandwidth in real-time and support virtualization technologies to maximize uptime and resilience, minimize latency, and ensure the most performance from each processing core. Together with congatec cloud API for distributed embedded edge servers, they provide the capabilities that data center managers need to remotely manage and monitor systems. These platforms also offer minimum latency for storage devices, as well as very fast access lanes to all the various sensor networks, field busses, and industrial Ethernets.

Embedded system design engineers and application engineers who want to utilize 10 GbE are invited to meet congatec’s expert for UK Jon Moseley. Visit congatec’s booth H6 for deeper insights into the roadmap and system design requirements for utilizing real-time technologies, or to request immediate platform availability through congatec’s exclusive early access program.

For more information about the congatec 10 GbE roadmap please visit the product page <http://www.congatec.com/en/technologies/com-express/com-express-type-7.html>

**About congatec AG**Headquartered in Deggendorf, Germany, congatec AG is a leading supplier of industrial computer modules using the standard form factors COM Express, Qseven and SMARC as well as single board computers and EDM services. congatec’s products can be used in a variety of industries and applications, such as industrial automation, medical, entertainment, transportation, telecommunication, test & measurement and point-of-sale. Core knowledge and technical know-how includes unique extended BIOS features as well as comprehensive driver and board support packages. Following the design-in phase, customers are given support via extensive product lifecycle management. The company’s products are manufactured by specialist service providers in accordance with modern quality standards. Currently congatec has entities in USA, Taiwan, China, Japan and Australia as well as United Kingdom, France, and the Czech Republic. More information is available on our website at <http://www.congatec.com/> or via [Facebook](http://www.facebook.com/Congatec), [Twitter](https://mobile.twitter.com/congatecAG) and [YouTube](http://www.youtube.com/congatecAE).

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